



July 2008

# FDP025N06

## N-Channel PowerTrench<sup>®</sup> MOSFET

60V, 265A, 2.5mΩ

### Features

- $R_{DS(on)} = 1.9m\Omega$  (Typ.) @  $V_{GS} = 10V$ ,  $I_D = 75A$
- Fast switching speed
- Low gate charge
- High performance trench technology for extremely low  $R_{DS(on)}$
- High power and current handling capability
- RoHS compliant

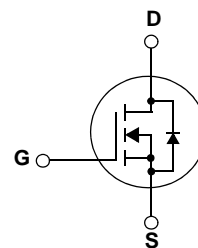
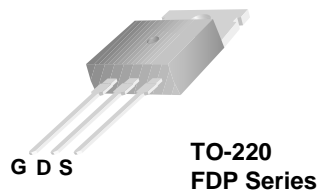


### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Application

- DC to DC convertors / Synchronous Rectification



### MOSFET Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

| Symbol         | Parameter  | Ratings   | Units      |
|----------------|--|---|------------|
| $V_{DSS}$      | Drain to Source Voltage  | 60  | V          |
| $V_{GSS}$      | Gate to Source Voltage   | $\pm 20$  | V          |
| $I_D$          | Drain Current  | - Continuous ( $T_C = 25^\circ C$ , Silicon Limited)  | 265*       |
|                |  | - Continuous ( $T_C = 100^\circ C$ , Silicon Limited) | 190*       |
|                |  | - Continuous ( $T_C = 25^\circ C$ , Package Limited)  | 120        |
| $I_{DM}$       | Drain Current - Pulsed (Note 1)  | 1060  | A          |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note 2)                                      | 2531  | mJ         |
| $dv/dt$        | Peak Diode Recovery $dv/dt$ (Note 3)   | 3.5   | V/ns       |
| $P_D$          | Power Dissipation ( $T_C = 25^\circ C$ )                                     | 395   | W          |
|                |  | - Derate above $25^\circ C$                           | 2.6        |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                                      | -55 to +175   | $^\circ C$ |
| $T_L$          | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | 300   | $^\circ C$ |

\*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 120A.

### Thermal Characteristics

| Symbol          | Parameter                               | Ratings | Units        |
|-----------------|---|---------|--------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case    | 0.38    | $^\circ C/W$ |
| $R_{\theta CS}$ | Thermal Resistance, Case to Sink Typ.   | 0.5     |              |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 62.5    |              |

FDP025N06 N-Channel PowerTrench<sup>®</sup> MOSFET

**Package Marking and Ordering Information**  $T_C = 25^\circ\text{C}$  unless otherwise noted

| Device Marking | Device    | Package | Reel Size | Tape Width | Quantity |
|----------------|-----------|---------|-----------|------------|----------|
| FDP025N06      | FDP025N06 | TO-220  | -         | -          | 50       |

**Electrical Characteristics**

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|--------|-----------|-----------------|------|------|------|-------|
|--------|-----------|-----------------|------|------|------|-------|

**Off Characteristics**

|                                      |   |  |    |      |           |                    |
|--------------------------------------|---|--|----|------|-----------|--------------------|
| $BV_{DSS}$                           | Drain to Source Breakdown Voltage         | $I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ , $T_C = 25^\circ\text{C}$ | 60 | -    | -         | V                  |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$                | -  | 0.04 | -         | $V/^\circ\text{C}$ |
| $I_{DSS}$                            | Zero Gate Voltage Drain Current           | $V_{DS} = 60\text{V}$ , $V_{GS} = 0\text{V}$                             | -  | -    | 1         | $\mu\text{A}$      |
|                                      |   | $V_{DS} = 60\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 150^\circ\text{C}$ | -  | -    | 500       |                    |
| $I_{GSS}$                            | Gate to Body Leakage Current              | $V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$                         | -  | -    | $\pm 100$ | nA                 |

**On Characteristics**

|              |                                      |   |     |     |     |                  |
|--------------|--------------------------------------|---|-----|-----|-----|------------------|
| $V_{GS(th)}$ | Gate Threshold Voltage               | $V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$          | 2.5 | 3.5 | 4.5 | V                |
| $R_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = 10\text{V}$ , $I_D = 75\text{A}$          | -   | 1.9 | 2.5 | $\text{m}\Omega$ |
| $g_{FS}$     | Forward Transconductance             | $V_{DS} = 10\text{V}$ , $I_D = 75\text{A}$ (Note 4) | -   | 200 | -   | S                |

**Dynamic Characteristics**

|              |                               |   |   |       |       |    |
|--------------|-------------------------------|---|---|-------|-------|----|
| $C_{iss}$    | Input Capacitance             | $V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$<br>$f = 1\text{MHz}$               | - | 11190 | 14885 | pF |
| $C_{oss}$    | Output Capacitance            |   | - | 1610  | 2140  | pF |
| $C_{rss}$    | Reverse Transfer Capacitance  |   | - | 750   | 1125  | pF |
| $Q_{g(tot)}$ | Total Gate Charge at 10V      | $V_{DS} = 48\text{V}$ , $I_D = 75\text{A}$<br>$V_{GS} = 10\text{V}$ (Note 4, 5) | - | 174   | 226   | nC |
| $Q_{gs}$     | Gate to Source Gate Charge    |   | - | 54    | -     | nC |
| $Q_{gd}$     | Gate to Drain "Miller" Charge |   | - | 50    | -     | nC |

**Switching Characteristics**

|              |                     |  |   |     |     |    |
|--------------|---------------------|--|---|-----|-----|----|
| $t_{d(on)}$  | Turn-On Delay Time  | $V_{DD} = 30\text{V}$ , $I_D = 75\text{A}$<br>$V_{GS} = 10\text{V}$ , $R_{GEN} = 25\Omega$ (Note 4, 5) | - | 134 | 278 | ns |
| $t_r$        | Turn-On Rise Time   |  | - | 324 | 658 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time |  | - | 348 | 706 | ns |
| $t_f$        | Turn-Off Fall Time  |  | - | 250 | 510 | ns |

**Drain-Source Diode Characteristics**

|                 |  |   |   |     |      |    |
|-----------------|--|---|---|-----|------|----|
| I <sub>S</sub>  | Maximum Continuous Drain to Source Diode Forward Current |   | - | -   | 265  | A  |
| I <sub>SM</sub> | Maximum Pulsed Drain to Source Diode Forward Current     |   | - | -   | 1060 | A  |
| V <sub>SD</sub> | Drain to Source Diode Forward Voltage                    | V <sub>GS</sub> = 0V, I <sub>SD</sub> = 75A | - | -   | 1.3  | V  |
| t <sub>rr</sub> | Reverse Recovery Time                                    | V <sub>GS</sub> = 0V, I <sub>SD</sub> = 75A | - | 69  | -    | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge                                  | dI <sub>F</sub> /dt = 100A/μs (Note 4)      | - | 152 | -    | nC |

**Notes:**

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2:  $L = 0.9\text{mH}$ ,  $I_{AS} = 75\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- 3:  $I_{SD} \leq 75\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
- 4: Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- 5: Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

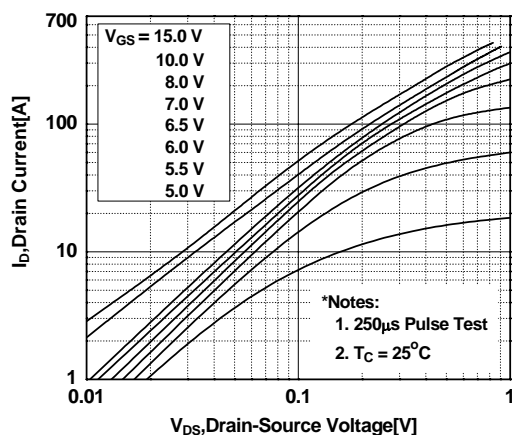


Figure 2. Transfer Characteristics

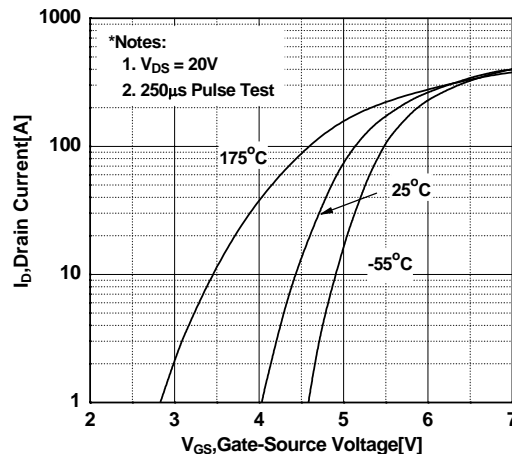


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

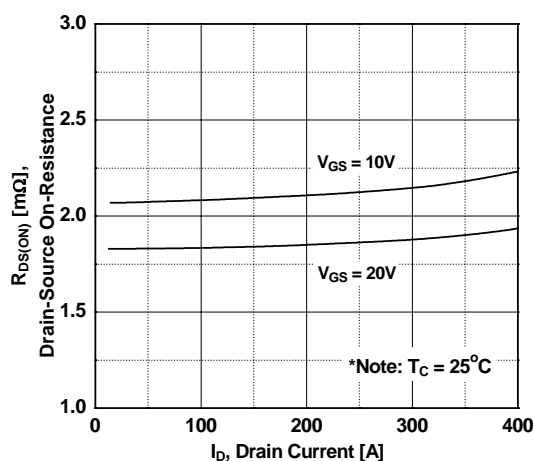


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

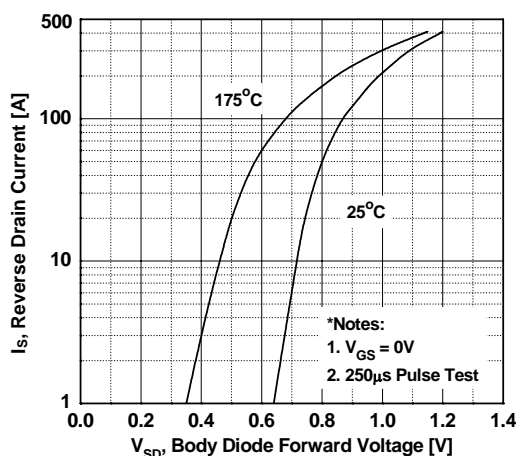


Figure 5. Capacitance Characteristics

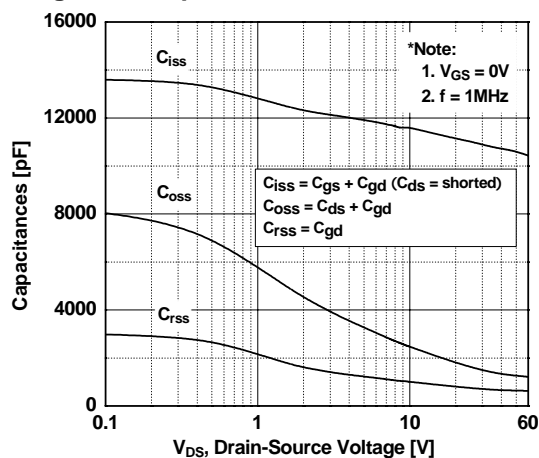
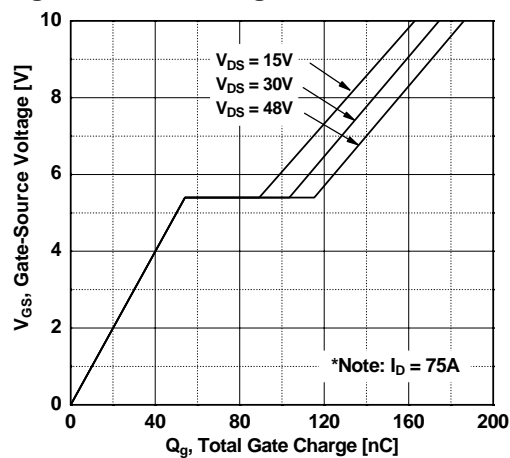


Figure 6. Gate Charge Characteristics



# Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

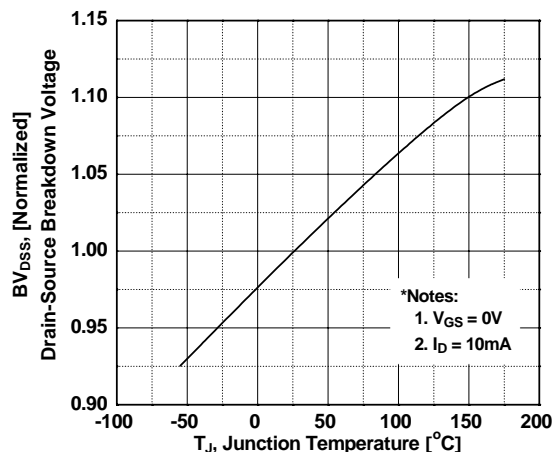


Figure 8. On-Resistance Variation vs. Temperature

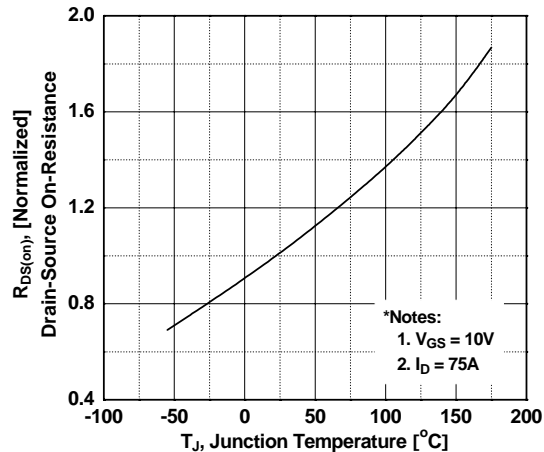


Figure 9. Maximum Safe Operating Area

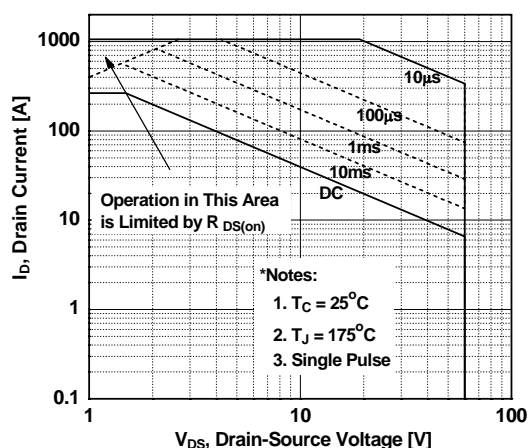


Figure 10. Maximum Drain Current vs. Case Temperature

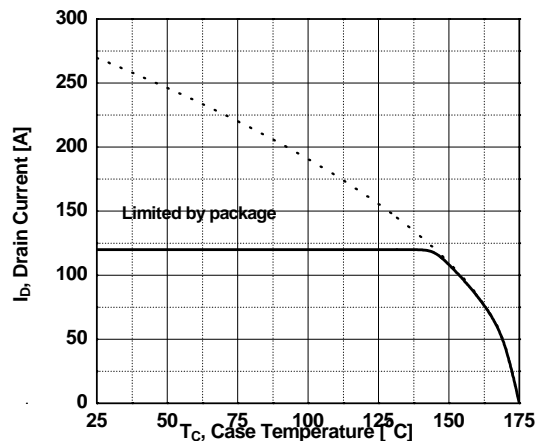
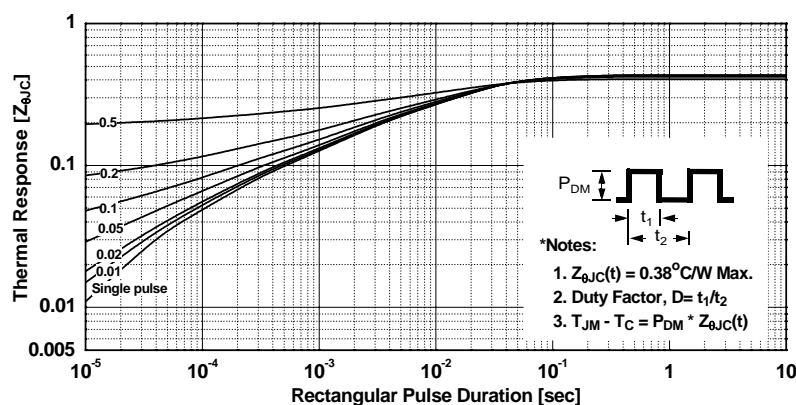
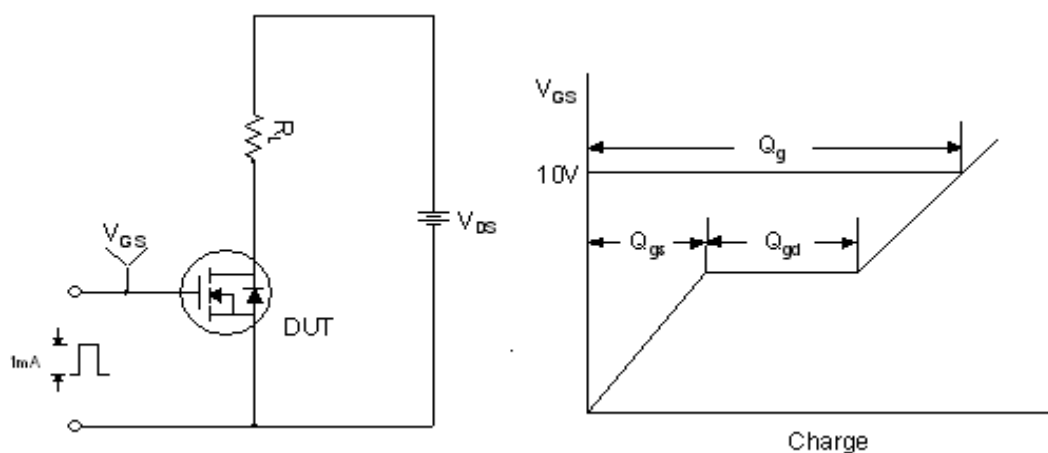


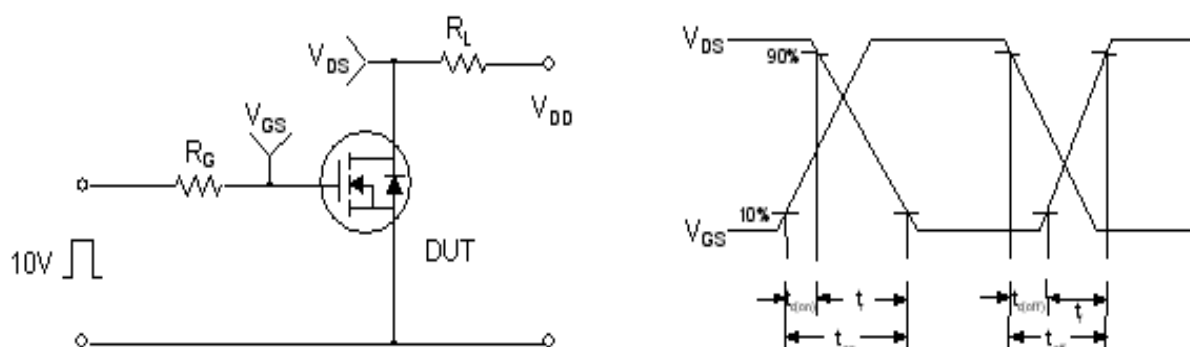
Figure 11. Transient Thermal Response Curve



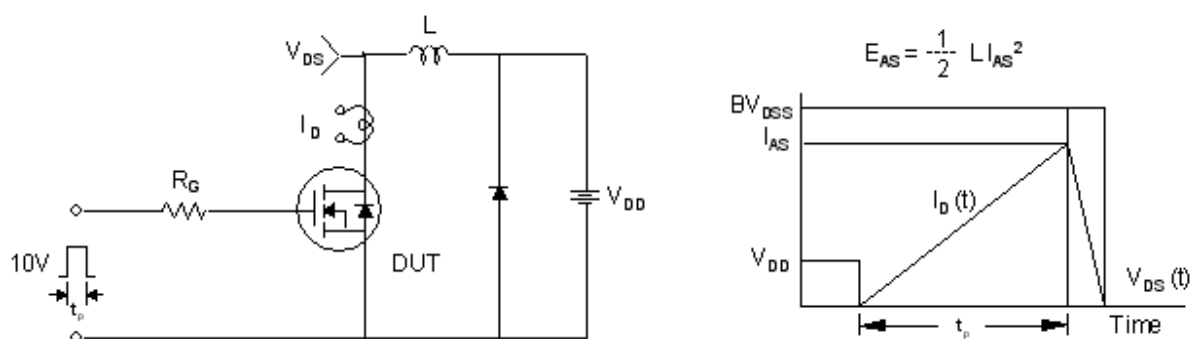
Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveforms



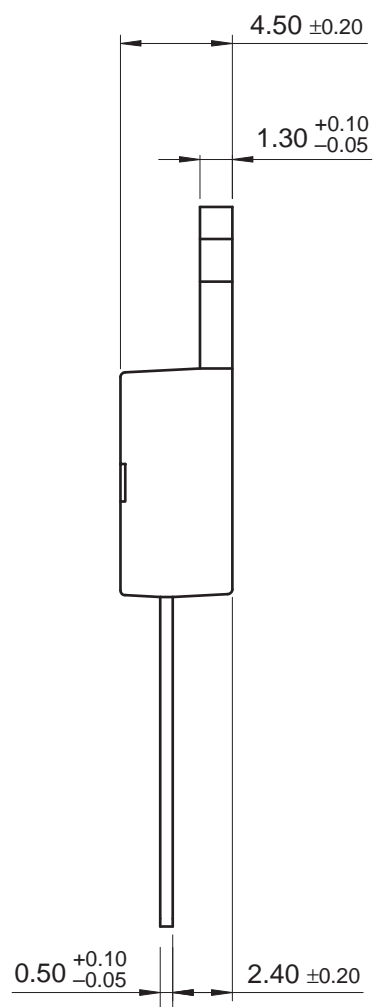
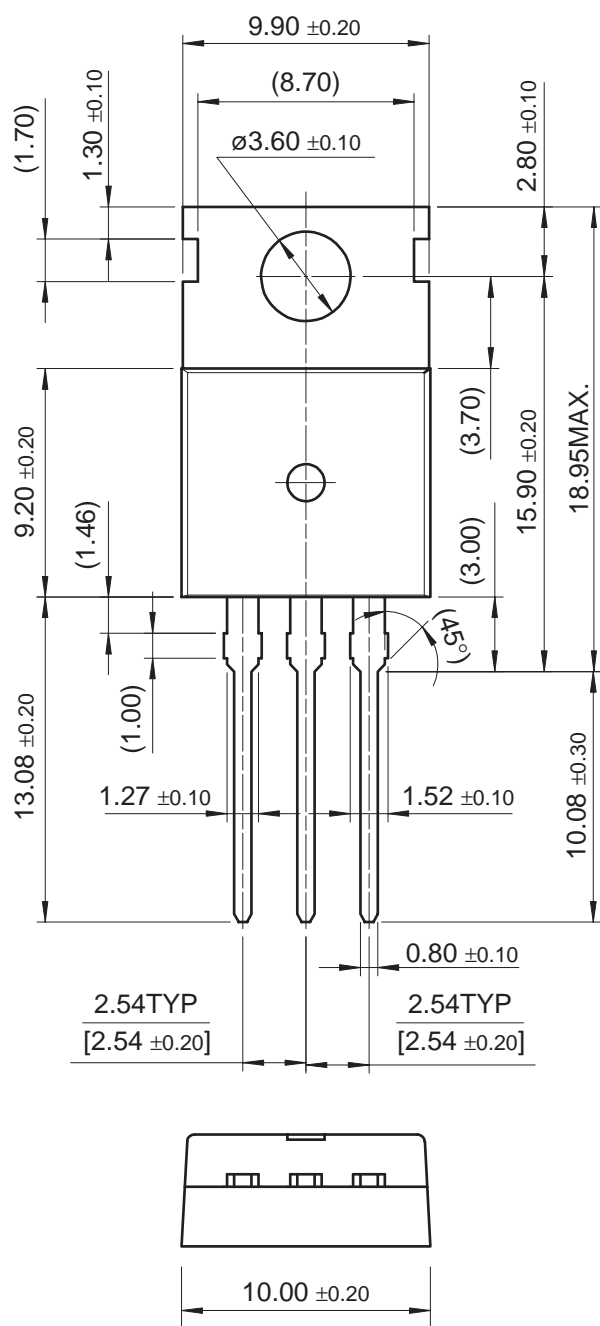
Unclamped Inductive Switching Test Circuit &amp; Waveforms





## Mechanical Dimensions

## TO-220





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